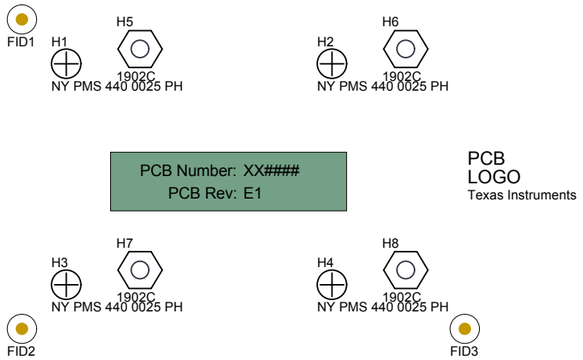

LBL1

PCB Label

Size: 0.65" x 0.20 "

ZZ1

Label Assembly Note

This Assembly Note is for PCB labels only

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

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Number: XX####	Rev: E1	Designed for: Public Release	Mod. Date: 5/30/2013
		Project Title: Change in menu Project|Project Options|Parameter	
		Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 1 of 1
Drawn By:		File: PMP7969_Hardware_ANSI-B.SchDoc	Size: B
Engineer: Enter name of project lead		Contact: http://www.ti.com/support	

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Revision History	
Revision	Notes

Place Block Diagram here (if appropriate) or delete this text box.
If using a block diagram from another tool, save the picture as a .bmp file.
Then, use menu Place|Drawing Tools|Graphic to insert the .bmp file on the schematic.

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Number: XX####	Rev: E1	Designed for: Public Release	Mod. Date: 5/30/2013
SVN Rev: Not in version control		Project Title: Change in menu Project|Project Options|Parameter	
Drawn By:		Sheet Title:	
Engineer: Enter name of project lead		Assembly Variant: 001	Sheet: 1 of 1
		File: PMP7969_Cover Sheet_ANSI-B.SchDoc	Size: B
		Contact: http://www.ti.com/support	

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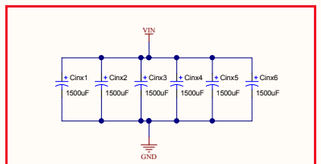

*NOTE: Cinx1 to Cinx6 were off the board and were used as input bulk capacitors as a bank of large decoupling caps in order to filter the input supply caused by long leads inherent in the test equipment setup.

Input Voltage = 9Vin to 16Vin

24Vout @ 25A max.

All components lying in this bordered box are located on the external enable/disable board.

Title			
Size D	Number		Revision
Date: 8/7/2013		Sheet of	
File: C:\Users\...\PMP7969 Schematics.SchDoc		Drawn By:	

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